

Kindly replace claim 1 with the following amended claim 1:

A1
1. (Amended) An array of resilient solder bonding structures, each one comprising a solder ball having a continuous curved exterior surface completely enclosing a first volume and having a completely enclosed interior cavity having a displacement constituting a second volume, the solder ball connecting at least one metal contact on a first surface to at least one metal contact on a second surface.

The changes in the previous claim are indicated by brackets for deletions and underlining for insertions.

1. (Amended) An array of resilient solder bonding structures, each one comprising a solder ball having a continuous curved exterior surface completely enclosing a first volume and having [an] a completely enclosed interior cavity having a displacement constituting a second volume, the solder ball connecting at least one metal contact on a first surface to at least one metal contact on a second surface.

Kindly replace claim 4 with the following amended claim 4:

A²
4. (Amended) A resilient ball grid array (BGA) electrical and mechanical attachment means for attaching an integrated circuit to a planar substrate, comprising a plurality of solder ball structures, each solder ball structure having a continuous curved exterior surface completely enclosing a first volume and having a completely enclosed interior cavity having a displacement constituting a second volume, each solder ball structure attaching one of a plurality of first metal contacts on the integrated circuit to an associated one of a plurality of second metal contacts on the planar substrate.

The changes in the previous claim are indicated by brackets for deletions and underlining for insertions.

4. (Amended) A resilient ball grid array (BGA) electrical and mechanical attachment means for attaching an integrated circuit to a planar substrate, comprising a plurality of solder ball structures, each solder ball structure having a continuous curved exterior surface completely enclosing a first volume and having [an] a completely enclosed interior cavity having a displacement constituting a second volume, each solder ball structure attaching one of a plurality of first metal contacts on the integrated circuit to an associated one of a plurality of second metal contacts on the planar substrate.

Kindly replace claim 7 with the following amended claim 7:

A3
7. (Amended) A resilient ball grid array (BGA) electrical and mechanical attachment means for attaching an integrated circuit to a printed circuit board, comprising a plurality of solder ball structures, each solder ball structure having a continuous curved exterior surface completely enclosing a first volume and having a completely enclosed interior cavity having a displacement constituting a second volume, each solder ball structure attaching one of a plurality of first metal contacts on the integrated circuit to an associated one of a plurality of second metal contacts on the printed circuit board.

The changes in the previous claim are indicated by brackets for deletions and underlining for insertions.

7. (Amended) A resilient ball grid array (BGA) electrical and mechanical attachment means for attaching an integrated circuit to a printed circuit board, comprising a plurality of solder ball structures, each solder ball structure having a continuous curved exterior surface completely enclosing a first volume and having [an] a completely enclosed interior cavity having a displacement constituting a second volume, each solder ball structure attaching one of a plurality of first metal contacts on the integrated circuit to an associated one of a plurality of second metal contacts on the printed circuit board.

Kindly replace claim 12 with the following amended claim 12:

12. (Amended) A resilient ball grid array (BGA) electrical and mechanical attachment means for attaching a first planar substrate to a second planar substrate, comprising a plurality of solder ball structures, each solder ball structure having a continuous curved exterior surface completely enclosing a first volume and having a completely enclosed interior cavity having a displacement constituting a second volume, each solder ball structure attaching one of a plurality of first metal contacts on the first planar substrate to an associated one of a plurality of second metal contacts on the second planar substrate.

The changes in the previous claim are indicated by brackets for deletions and underlining for insertions.

12. (Amended) A resilient ball grid array (BGA) electrical and mechanical attachment means for attaching a first planar substrate to a second planar substrate, comprising a plurality of solder ball structures, each solder ball structure having a continuous curved exterior surface completely enclosing a first volume and having [an] a completely enclosed interior cavity having a displacement constituting a second volume, each solder ball structure attaching one of a plurality of first metal contacts on the first planar substrate to an associated one of a plurality of second metal contacts on the second planar substrate.